SN54165, SN54LS165A, SN74165, SN74LS165A PARALLEL-LOAD 8-BIT SHIFT REGISTERS

The SN54165 and SN74165 devices are obsolete and are no longer supplied.

SDLS062D - OCTOBER 1976 - REVISED FEBRUARY 2002

- Complementary Outputs
- Direct Overriding Load (Data) Inputs
- Gated Clock Inputs
- Parallel-to-Serial Data Conversion

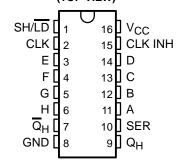
TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
'165	26 MHz	210 mW
'LS165A	35 MHz	90 mW

description

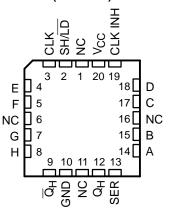
The '165 and 'LS165A are 8-bit serial shift registers that shift the data in the direction of Q_A toward Q_H when clocked. Parallel-in access to each stage is made available by eight individual, direct data inputs that are enabled by a low level at the shift/load (SH/ \overline{LD}) input. These registers also feature gated clock (CLK) inputs and complementary outputs from the eighth bit. All inputs are diode-clamped to minimize transmission-line effects, thereby simplifying system design.

Clocking is accomplished through a two-input positive-NOR gate, permitting one input to be used as a clock-inhibit function. Holding either of the clock inputs high inhibits clocking, and holding either clock input low with SH/LD high enables the other clock input. Clock inhibit (CLK INH) should be changed to the high level only while CLK is high. Parallel loading is inhibited as long as SH/LD is high. Data at the parallel inputs are loaded directly into the register while SH/LD is low, independently of the levels of CLK, CLK INH, or serial (SER) inputs.

SN54165, SN54LS165A . . . J OR W PACKAGE SN74165 . . . N PACKAGE SN74LS165A . . . D, N, OR NS PACKAGE (TOP VIEW)



SN54LS165A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



The SN54165 and SN74165 devices are obsolete and are no longer supplied.

SDLS062D - OCTOBER 1976 - REVISED FEBRUARY 2002

ORDERING INFORMATION

TA	PAC	KAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74LS165AN	SN74LS165AN
0°C to 70°C	SOIC - D	Tube	SN74LS165AD	LS165A
0 0 10 70 0	30IC - D	Tape and reel	SN74LS165ADR	L3103A
	SOP - NS	Tape and reel	SN74LS165ANSR	74LS165A
	CDIP – J	Tube	SN54LS165AJ	SN54LS165AJ
_55°C to 125°C	CDIF - J	Tube	SNJ54LS165AJ	SNJ54LS165AJ
_33 C to 125 C	CFP – W	Tube	SNJ54LS165AW	SNJ54LS165AW
	LCCC - FK	Tube	SNJ54LS165AFK	SNJ54LS165AFK

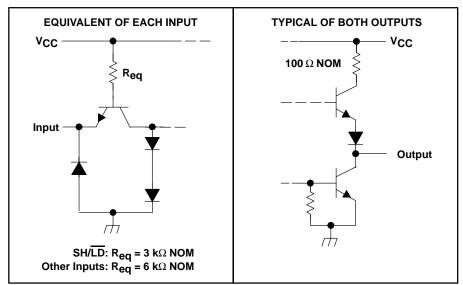
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

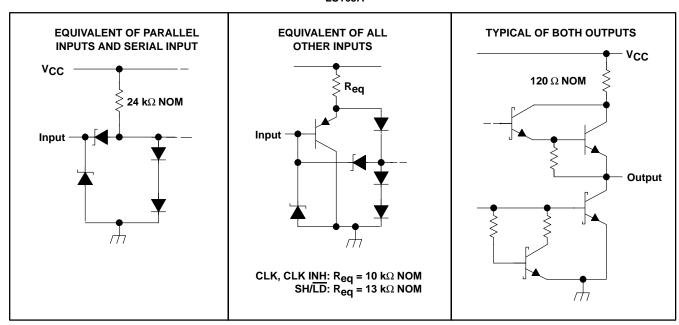
		INPUTS	5		l	RNAL PUTS	OUTPUT
SH/LD	CLK INH	CLK	SER	PARALLEL AH	\overline{Q}_A	\overline{Q}_B	QH
L	Х	Χ	Χ	ah	а	b	h
Н	L	L	Χ	Х	Q _{A0}	Q_{B0}	Q _{H0}
Н	L	\uparrow	Н	Х	Н	Q_{An}	Q_{Gn}
Н	L	\uparrow	L	Х	L	Q_{An}	Q _{Gn}
Н	Н	Χ	Χ	X	Q _{A0}	Q_{B0}	Q _{H0}

schematics of inputs and outputs

'165

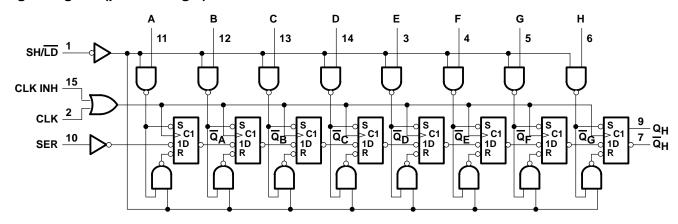


'LS165A



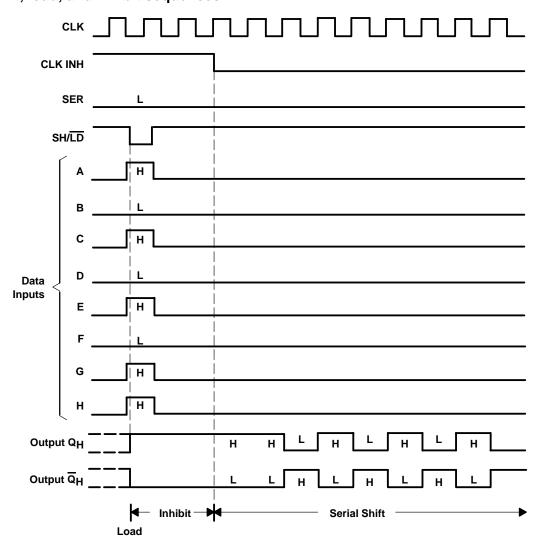
SDLS062D - OCTOBER 1976 - REVISED FEBRUARY 2002

logic diagram (positive logic)



Pin numbers shown are for D, J, N, NS, and W packages.

typical shift, load, and inhibit sequences



SN54165, SN54LS165A, SN74165, SN74LS165A PARALLEL-LOAD 8-BIT SHIFT REGISTERS

The SN54165 and SN74165 devices are obsolete and are no longer supplied.

SDLS062D - OCTOBER 1976 - REVISED FEBRUARY 2002

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)		
Input voltage, V _I : SN54165, SN74	165	5.5 V
SN54LS165A, S	N74LS165A	7 V
Interemitter voltage (see Note 2)		5.5 V
Package thermal impedance θ _{JA} (se	ee Note 3): D package	
-	N package	67°C/W
	NS package	64°C/W
Storage temperature range, T _{sta}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.
 - 2. This is the voltage between two emitters of a multiple-emitter transistor. This rating applies for the '165 to the SH/LD input in conjunction with the CLK INH input.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			SN54165		9	N74165		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
IOH	High-level output current			-800			-800	μΑ
loL	Low-level output current			16			16	mA
f _{clock}	Clock frequency	0		20	0		20	MHz
tw(clock)	Width of clock input pulse	25			25			ns
tw(load)	Width of load input pulse	15			15			ns
t _{su}	Clock-enable setup time (see Figure 1)	30			30			ns
t _{su}	Parallel input setup time (see Figure 1)	10			10			ns
t _{su}	Serial input setup time (see Figure 1)	20			20			ns
t _{su}	Shift setup time (see Figure 1)	45			45			ns
t _h	Hold time at any input	0			0			ns
T _A	Operating free-air temperature	-55		125	0		70	°C



SDLS062D - OCTOBER 1976 - REVISED FEBRUARY 2002

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	242445752			t	,	SN54165		,	SN74165	i	
	PARAMETER		I IESI CO	NDITIONS†	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage	gh-level input voltage			2			2			V
VIL	Low-level input voltage						0.8			0.8	V
VIK	Input clamp voltage		$V_{CC} = MIN,$	I _I = -12 mA			-1.5			-1.5	V
VOH	High-level output voltage	output voltage		$V_{IH} = 2 \text{ V},$ $I_{OH} = -800 \mu\text{A}$	2.4	3.4		2.4	3.4		V
VOL	Low-level output voltage	w-level output voltage		V _{IH} = 2 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
IĮ	Input current at maximum	n input voltage	$V_{CC} = MAX$,	V _I = 5.5 V			1			1	mA
1	High lovel input current	SH/LD	Vaa Max	V: 2.4.V			80			80	
¹IH	High-level input current	Other inputs	$V_{CC} = MAX,$	V = 2.4 V			40			40	μΑ
1	SH/LD		VMAY	V: - 0.4 V			-3.2			-3.2	mA
'IL	Low-level input current Other inputs		$V_{CC} = MAX,$	V = 0.4 V			-1.6			-1.6	IIIA
los	OS Short-circuit output current§		$V_{CC} = MAX$		-20		-55	-18		-55	mA
ICC	Supply current		$V_{CC} = MAX$,	See Note 4		42	63		42	63	mA

NOTE 4: With the outputs open, CLK INH and CLK at 4.5 V, and a clock pulse applied to SH/LD, I_{CC} is measured first with the parallel inputs at 4.5 V, then with the parallel inputs grounded.

SN54165 and SN74165 switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see Figure 1)

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				20	26		MHz
^t PLH	LD	Any	$C_L = 15 pF, R_L = 400 \Omega$		21	31	ns
^t PHL	LD	Arry	OL = 13 pr, KL = 400 s2		27	40	115
^t PLH	CLK	Any	$C_L = 15 \text{ pF, } R_L = 400 \Omega$		16	24	ns
^t PHL	OLK	Ally	OL = 13 pr , 11 = 400 sz		21	31	115
^t PLH	Н	0	$C_L = 15 \text{ pF, } R_L = 400 \Omega$		11	17	ns
^t PHL	11	Q _H	OL = 13 pr, KL = 400 \$2		24	36	115
^t PLH	н	$\overline{\mathtt{Q}}_{H}$	C: - 15 pE P: - 400 O		18	27	no
^t PHL	17	¥H	$C_L = 15 \text{ pF}, R_L = 400 \Omega$		18	27	ns

[¶] f_{max} = maximum clock frequency, t_{PLH} = propagation delay time, low-to-high-level output, t_{PHL} = propagation delay time, high-to-low-level output

[†] For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

SDLS062D - OCTOBER 1976 - REVISED FEBRUARY 2002

recommended operating conditions

			SN	54LS16	5A	SN	74LS165	δA	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.7			0.8	V
IOH	High-level output current				-0.4			-0.4	mA
l _{OL}	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		25	MHz
4 () ()	Width of clock input pulse (see Figure 2)	Clock high	15			15			ns
^t w(clock)	whath of clock input pulse (see Figure 2)	Clock low	25			25			115
+ 4	Width of load input pulse	Clock high	25			25			ns
^t w(load)	whath of load input pulse	Clock low	17			17			115
t _{su}	Clock-enable setup time (see Figure 2)		30			30			ns
t _{su}	Parallel input setup time (see Figure 2)		10			10			ns
t _{su}	Serial input setup time (see Figure 2)		20			20			ns
t _{su}	Shift setup time (see Figure 2)		45			45			ns
^t h	Hold time at any input		0			0			ns
T _A	Operating free-air temperature		-55	_	125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEOT	CNDITIONS		SN	154LS16	5A	SN	74LS16	5A	
PARAMETER		1651 0	CONDITIONS		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = MIN,$	$I_{I} = -18 \text{ mA}$					-1.5			-1.5	V
Voн	$V_{CC} = MIN,$	V _{IH} = 2 V,	$V_{IL} = MAX$,	$I_{OH} = -0.4 \text{ mA}$	2.5	3.5		2.7	3.5		V
Voi	V _{CC} = MIN,	\/ 2\/	\/ MAY	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
VOL	AGG = MIIA	ν IH = 2 ν,	VIC = IVIAA	I _{OL} = 8 mA					0.35	0.5	V
lį	$V_{CC} = MAX$,	V _I = 7 V					0.1			0.1	mA
ΙΗ	$V_{CC} = MAX$,	V _I = 2.7 V					20			20	μΑ
IIL	$V_{CC} = MAX$,	V _I = 0.4 V					-0.4			-0.4	mA
I _{OS} §	$V_{CC} = MAX$			•	-20		-100	-20		-100	mA
ICC	$V_{CC} = MAX$,	See Note 4				18	30		18	30	mA

NOTE 4. With the outputs open, CLK INH and CLK at 4.5 V, and a clock pulse applied to SH/LD, I_{CC} is measured first with the parallel inputs at 4.5 V, then with the parallel inputs grounded.



[†] For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

SN54165, SN54LS165A, SN74165, SN74LS165A PARALLEL-LOAD 8-BIT SHIFT REGISTERS

SDLS062D - OCTOBER 1976 - REVISED FEBRUARY 2002

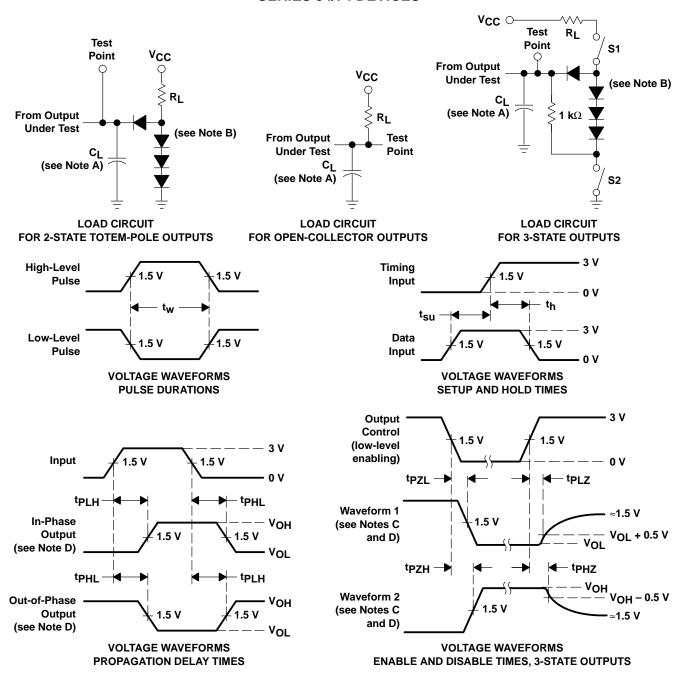
The SN54165 and SN74165 devices are obsolete and are no longer supplied.

SN54LS165A and SN74LS165A switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 2)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				25	35		MHz
t _{PLH}	<u>ID</u>	Any	$R_L = 2 k\Omega$, $C_L = 15 pF$		21	35	ns
t _{PHL}	LD	Arry	N_ = 2 ks2, G_ = 15 pr		26	35	115
^t PLH	CLK	Any	$R_{\parallel} = 2 \text{ k}\Omega, C_{\parallel} = 15 \text{ pF}$		14	25	ns
^t PHL	OLK	Ally	N _L = 2 N ₂ 2, O _L = 10 pi		16	25	113
^t PLH	Н	0	$R_L = 2 k\Omega$, $C_L = 15 pF$		13	25	ns
^t PHL	11	Q _H	N _L = 2 κ ₂₂ , G _L = 15 pr		24	30	115
^t PLH	Н	<u></u>	D. 240 C. 45 pF		19	30	
t _{PHL}	П	\overline{Q}_H	$R_L = 2 k\Omega$, $C_L = 15 pF$		17	25	ns

[†] f_{max} = maximum clock frequency, t_{PLH} = propagation delay time, low-to-high-level output, t_{PHL} = propagation delay time, high-to-low-level output

PARAMETER MEASUREMENT INFORMATION **SERIES 54/74 DEVICES**

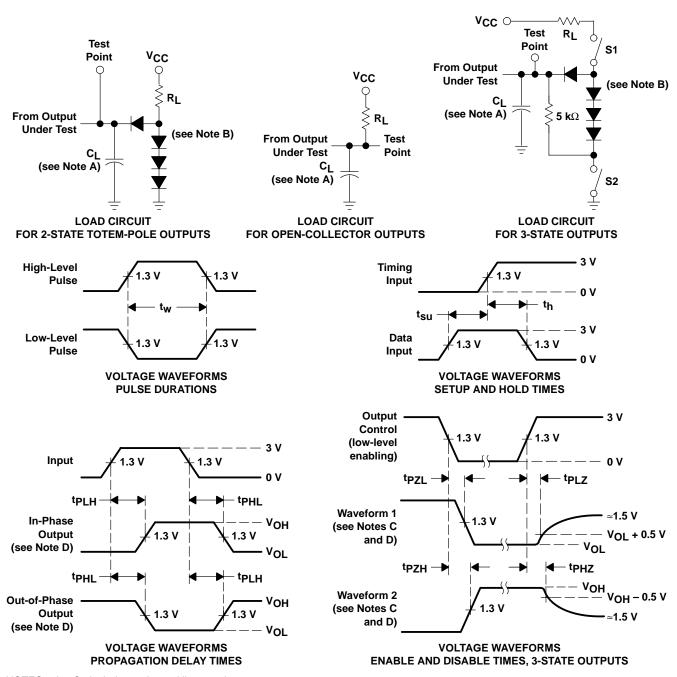


- NOTES: A. C_L includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - D. S1 and S2 are closed for tpLH, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
 - E. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_0 \approx 50 \Omega$; t_f and $t_f \leq$ 7 ns for Series 54/74 devices and t_r and $t_f \le 2.5$ ns for Series 54S/74S devices.
 - F. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION **SERIES 54LS/74LS DEVICES**



- NOTES: A. C_L includes probe and jig capacitance.
 - B. All diodes are 1N3064 or equivalent.
 - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - D. S1 and S2 are closed for tpLH, tpHL, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
 - E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
 - All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O \approx 50 \ \Omega$, $t_r \leq 1.5 \ ns$, $t_f \leq 2.6 \ ns$.
 - The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms







15-Apr-2017

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7700601VEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-7700601VE A SNV54LS165AJ	Samples
5962-7700601VFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-7700601VF A SNV54LS165AW	Samples
7700601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700601EA SNJ54LS165AJ	Samples
7700601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700601FA SNJ54LS165AW	Samples
JM38510/30608B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30608B2A	Samples
JM38510/30608BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30608BEA	Samples
JM38510/30608BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30608BFA	Samples
M38510/30608B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30608B2A	Samples
M38510/30608BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30608BEA	Samples
M38510/30608BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30608BFA	Samples
SN54LS165AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS165AJ	Samples
SN74LS165AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS165A	Samples
SN74LS165ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS165A	Samples
SN74LS165ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS165A	Samples
SN74LS165ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS165A	Samples
SN74LS165ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS165A	Samples



PACKAGE OPTION ADDENDUM

15-Apr-2017

Orderable Device	Status	Package Type	_	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74LS165AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS165AN	Samples
SN74LS165ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS165AN	Samples
SN74LS165ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS165A	Samples
SNJ54LS165AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 165AFK	Samples
SNJ54LS165AJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700601EA SNJ54LS165AJ	Samples
SNJ54LS165AW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700601FA SNJ54LS165AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

15-Apr-2017

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LS165A, SN54LS165A-SP, SN74LS165A:

Catalog: SN74LS165A, SN54LS165A

Military: SN54LS165A

Space: SN54LS165A-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

www.ti.com 8-Apr-2013

TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS165ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

www.ti.com 8-Apr-2013



*All dimensions are nominal

Device Package Type		Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LS165ADR	SOIC	D	16	2500	333.2	345.9	28.6	

IMPORTANT NOTICE

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.